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NEW CLAIMS

17. (New) An electronic device according to claim 1, wherein said electric connection means between said connection pins and the connection pads of said silicon die are made by welded thin bonding wires.
18. (New) An electronic device according to claim 1, wherein said electronic device is partially packaged in a resin so as to comprise a semi-package, that covers a first surface of the die where said connection pads are arranged together with said connection means between said connection pins and the connection pads, as well as all flanks of the die, leaving an opposite, second surface of the die exposed.
19. (New) An electronic device according to claim 1, wherein the pre-formed portion not encapsulated by resin is a portion of a bent metal pin.
20. (New) An electronic device according to claim 1, wherein said connection means for removable attachment of said pins to said silicon die is a double-sided adhesive tape or a glue.